

# 100ppm/°C, 50μA in SOT23-3 CMOS VOLTAGE REFERENCE

## FEATURES

- **MicroSIZE PACKAGE:** SOT23-3
- **LOW DROPOUT:** 1mV
- **HIGH OUTPUT CURRENT:** 25mA
- **LOW TEMPERATURE DRIFT:** 100ppm/°C max
- **HIGH ACCURACY:** 2%
- **LOW I<sub>Q</sub>:** 50μA max

## APPLICATIONS

- **PORTABLE, BATTERY-POWERED EQUIPMENT**
- **DATA ACQUISITION SYSTEMS**
- **MEDICAL EQUIPMENT**
- **HAND-HELD TEST EQUIPMENT**

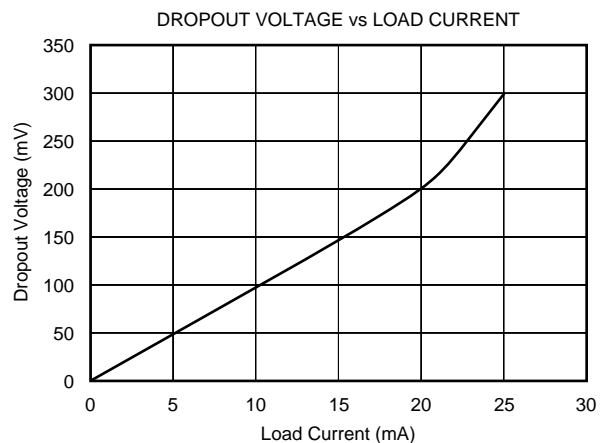
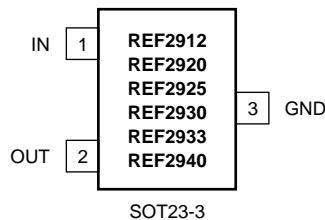
## DESCRIPTION

The REF29xx is a precision, low-power, low-voltage dropout voltage reference family available in a tiny SOT23-3.

The REF29xx small size and low power consumption (50μA max) make it ideal for portable and battery-powered applications. The REF29xx does not require a load capacitor, but is stable with any capacitive load.

Unloaded, the REF29xx can be operated with supplies within 1mV of output voltage. All models are specified for the wide temperature range, -40°C to +125°C.

PRODUCT	VOLTAGE (V)
REF2912	1.25
REF2920	2.048
REF2925	2.5
REF2930	3.0
REF2933	3.3
REF2940	4.096



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Supply Voltage, V+ to V- .....	7.0V
Output Short-Circuit <sup>(2)</sup> .....	Continuous
Operating Temperature .....	-40°C to +125°C
Storage Temperature .....	-65°C to +125°C
Junction Temperature .....	+150°C
Lead Temperature (soldering, 10s) .....	+300°C

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these, or any other conditions beyond those specified, is not implied.  
(2) Short-circuit to ground.



## ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## PACKAGE/ORDERING INFORMATION<sup>(1)</sup>

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR <sup>(1)</sup>	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
REF2912	SOT23-3	DBZ	-40°C to +125°C	R29A	REF2912AIDBZT	Tape and Reel, 250
"	"	"	"	"	REF2912AIDBZR	Tape and Reel, 3000
REF2920	SOT23-3	DBZ	-40°C to +125°C	R29B	REF2920AIDBZT	Tape and Reel, 250
"	"	"	"	"	REF2920AIDBZR	Tape and Reel, 3000
REF2925	SOT23-3	DBZ	-40°C to +125°C	R29C	REF2925AIDBZT	Tape and Reel, 250
"	"	"	"	"	REF2925AIDBZR	Tape and Reel, 3000
REF2930	SOT23-3	DBZ	-40°C to +125°C	R29D	REF2930AIDBZT	Tape and Reel, 250
"	"	"	"	"	REF2930AIDBZR	Tape and Reel, 3000
REF2933	SOT23-3	DBZ	-40°C to +125°C	R29E	REF2933AIDBZT	Tape and Reel, 250
"	"	"	"	"	REF2933AIDBZR	Tape and Reel, 3000
REF2940	SOT23-3	DBZ	-40°C to +125°C	R29F	REF2940AIDBZT	Tape and Reel, 250
"	"	"	"	"	REF2940AIDBZR	Tape and Reel, 3000

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this data sheet, or see the TI web site at [www.ti.com](http://www.ti.com).

## ELECTRICAL CHARACTERISTICS

**Boldface** limits apply over the specified temperature range,  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .

At  $T_A = +25^\circ\text{C}$ ,  $I_{\text{LOAD}} = 0\text{mA}$ ,  $V_{\text{IN}} = 5\text{V}$ , unless otherwise noted.

PARAMETER	CONDITIONS	REF29xx			UNITS
		MIN	TYP	MAX	
<b>REF2912-1.25V</b>					
<b>OUTPUT VOLTAGE</b> Initial Accuracy	$V_{\text{OUT}}$	1.225	1.25	1.275 2	V %
<b>NOISE</b> Output Voltage Noise Voltage Noise	$f = 0.1\text{Hz to }10\text{Hz}$ $f = 10\text{Hz to }10\text{kHz}$		14 42		$\mu\text{V}_{\text{PP}}$ $\mu\text{V}_{\text{RMS}}$
<b>LINE REGULATION</b>	$1.8\text{V} \leq V_{\text{IN}} \leq 5.5\text{V}$		60	190	$\mu\text{V/V}$
<b>REF2920</b>					
<b>OUTPUT VOLTAGE</b> Initial Accuracy	$V_{\text{OUT}}$	2.007	2.048	2.089 2	V %
<b>NOISE</b> Output Voltage Noise Voltage Noise	$f = 0.1\text{Hz to }10\text{Hz}$ $f = 10\text{Hz to }10\text{kHz}$		23 65		$\mu\text{V}_{\text{PP}}$ $\mu\text{V}_{\text{RMS}}$
<b>LINE REGULATION</b>	$V_{\text{REF}} + 50\text{mV} \leq V_{\text{IN}} \leq 5.5\text{V}$		110	290	$\mu\text{V/V}$
<b>REF2925</b>					
<b>OUTPUT VOLTAGE</b> Initial Accuracy	$V_{\text{OUT}}$	2.450	2.50	2.550 2	V %
<b>NOISE</b> Output Voltage Noise Voltage Noise	$f = 0.1\text{Hz to }10\text{Hz}$ $f = 10\text{Hz to }10\text{kHz}$		28 80		$\mu\text{V}_{\text{PP}}$ $\mu\text{V}_{\text{RMS}}$
<b>LINE REGULATION</b>	$V_{\text{REF}} + 50\text{mV} \leq V_{\text{IN}} \leq 5.5\text{V}$		120	325	$\mu\text{V/V}$

# ELECTRICAL CHARACTERISTICS (Cont.)

**Boldface** limits apply over the specified temperature range,  $T_A = -40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .

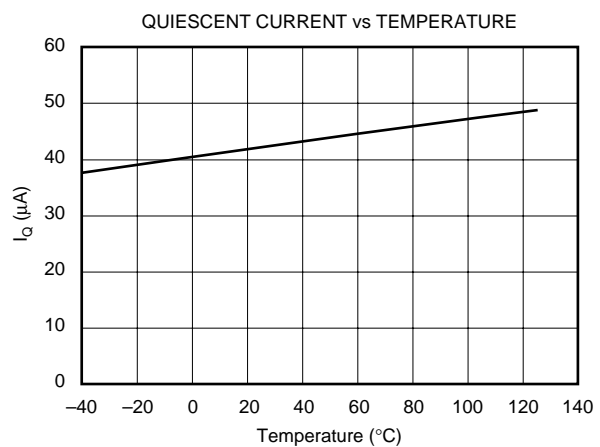
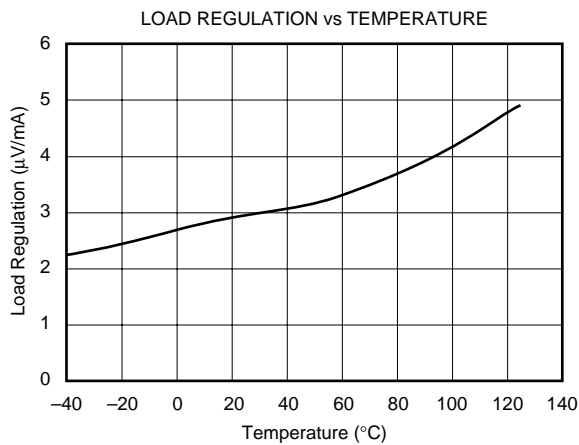
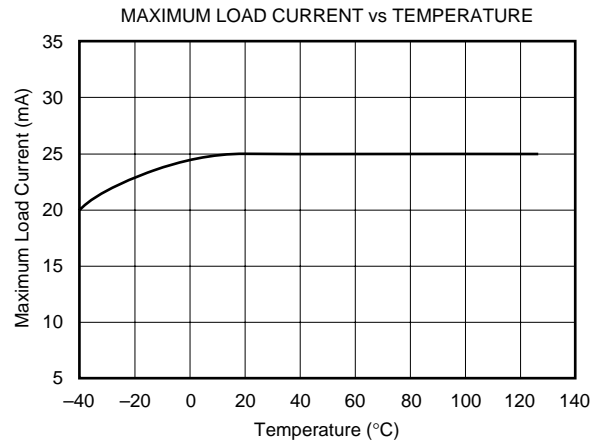
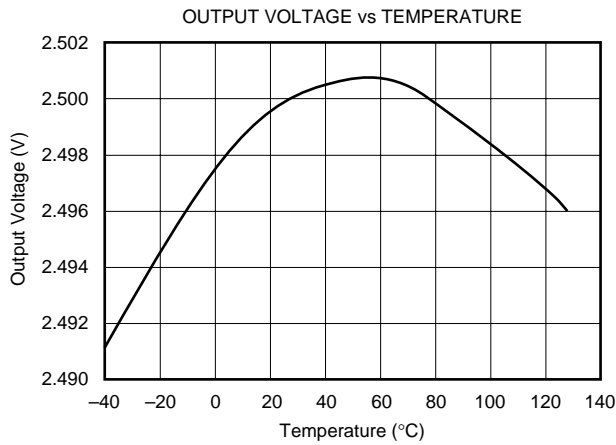
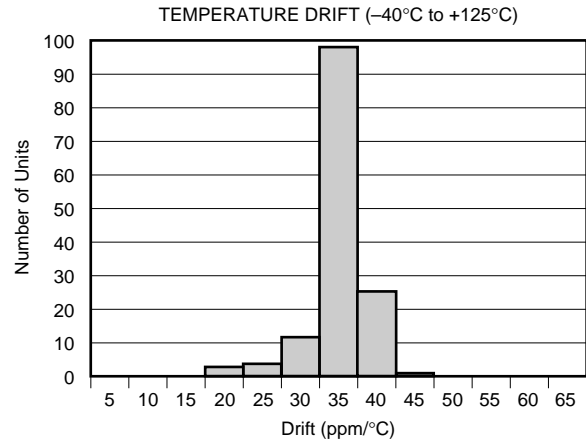
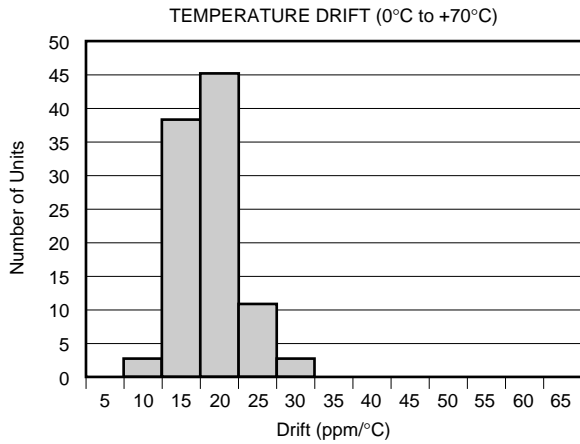
At  $T_A = +25^{\circ}\text{C}$ ,  $I_{\text{LOAD}} = 0\text{mA}$ ,  $V_{\text{IN}} = 5\text{V}$ , unless otherwise noted.

PARAMETER	CONDITIONS	REF29xx			UNITS
		MIN	TYP	MAX	
<b>REF2930</b>					
<b>OUTPUT VOLTAGE</b> Initial Accuracy	$V_{\text{OUT}}$	2.940	3.0	3.06 2	V %
<b>NOISE</b> Output Voltage Noise Voltage Noise	$f = 0.1\text{Hz to }10\text{Hz}$ $f = 10\text{Hz to }10\text{kHz}$		33 94		$\mu\text{V}_{\text{PP}}$ $\mu\text{V}_{\text{RMS}}$
<b>LINE REGULATION</b>	$V_{\text{REF}} + 50\text{mV} \leq V_{\text{IN}} \leq 5.5\text{V}$		120	375	$\mu\text{V}/\text{V}$
<b>REF2933</b>					
<b>OUTPUT VOLTAGE</b> Initial Accuracy	$V_{\text{OUT}}$	3.234	3.30	3.366 2	V %
<b>NOISE</b> Output Voltage Noise Voltage Noise	$f = 0.1\text{Hz to }10\text{Hz}$ $f = 10\text{Hz to }10\text{kHz}$		36 105		$\mu\text{V}_{\text{PP}}$ $\mu\text{V}_{\text{RMS}}$
<b>LINE REGULATION</b>	$V_{\text{REF}} + 50\text{mV} \leq V_{\text{IN}} \leq 5.5\text{V}$		130	400	$\mu\text{V}/\text{V}$
<b>REF2940</b>					
<b>OUTPUT VOLTAGE</b> Initial Accuracy	$V_{\text{OUT}}$	4.014	4.096	4.178 2	V %
<b>NOISE</b> Output Voltage Noise Voltage Noise	$f = 0.1\text{Hz to }10\text{Hz}$ $f = 10\text{Hz to }10\text{kHz}$		45 128		$\mu\text{V}_{\text{PP}}$ $\mu\text{V}_{\text{RMS}}$
<b>LINE REGULATION</b>	$V_{\text{REF}} + 50\text{mV} \leq V_{\text{IN}} \leq 5.5\text{V}$		160	410	$\mu\text{V}/\text{V}$
<b>REF2912, REF2920, REF2925, REF2930, REF2933, REF2940</b>					
<b>OUTPUT VOLTAGE TEMP DRIFT</b> <sup>(2)</sup>	$dV_{\text{OUT}}/dT$	$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$		<b>35</b> <b>100</b>	<b>ppm/°C</b> mA
<b>OUTPUT CURRENT</b>	$I_{\text{LOAD}}$				25
<b>LONG-TERM STABILITY</b>		0-1000 <sub>H</sub> 1000-2000 <sub>H</sub>		24 15	ppm ppm
<b>LOAD REGULATION</b> <sup>(3)</sup>	$dV_{\text{OUT}}/dI_{\text{LOAD}}$	$0\text{mA} < I_{\text{LOAD}} < 25\text{mA}$ , $V_{\text{IN}} = V_{\text{REF}} + 500\text{mV}$ <sup>(1)</sup>		3	100
<b>THERMAL HYSTERESIS</b> <sup>(4)</sup>	$dT$			25	100
<b>DROPOUT VOLTAGE</b>	$V_{\text{IN}} - V_{\text{OUT}}$			1	50
<b>SHORT-CIRCUIT CURRENT</b>	$I_{\text{SC}}$			45	
<b>TURN-ON SETTLING TIME</b>		to 0.1% at $V_{\text{IN}} = 5\text{V}$ with $C_L = 0$		120	
<b>POWER SUPPLY</b> Voltage Over Temperature Quiescent Current Over Temperature	$V_S$  $I_Q$	$I_L = 0$ $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	$V_{\text{REF}} + 0.001$ <sup>(5)</sup> <b><math>V_{\text{REF}} + 0.05</math></b>		5.5 <b>5.5</b> 50 <b>59</b>
<b>TEMPERATURE RANGE</b> Specified Range Operating Range Storage Range Thermal Resistance SOT23-3 Surface-Mount	    $\theta_{\text{JC}}$ $\theta_{\text{JA}}$				     110 336
					°C °C °C °C/W °C/W

NOTES: (1) Minimum supply voltage for REF2912 is 1.8V. (2) Box Method used to determine over temperature drift. (3) Typical value of load regulation reflects measurements using a force and sense contacts, see text "Load Regulation". (4) Thermal hysteresis procedure is explained in more detail in Applications Information section of data sheet. (5) For  $I_L > 0$ , see Typical Characteristic curves.

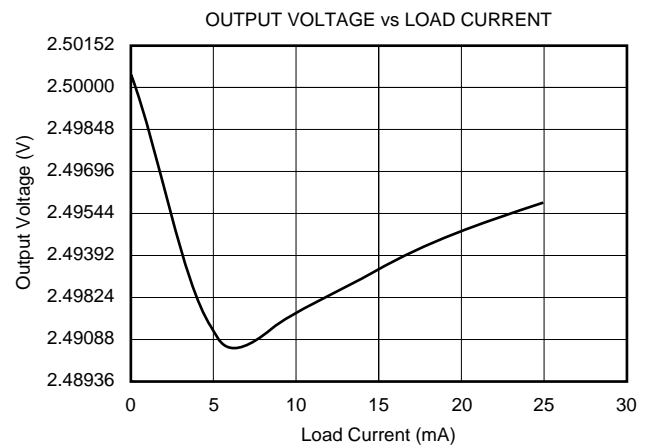
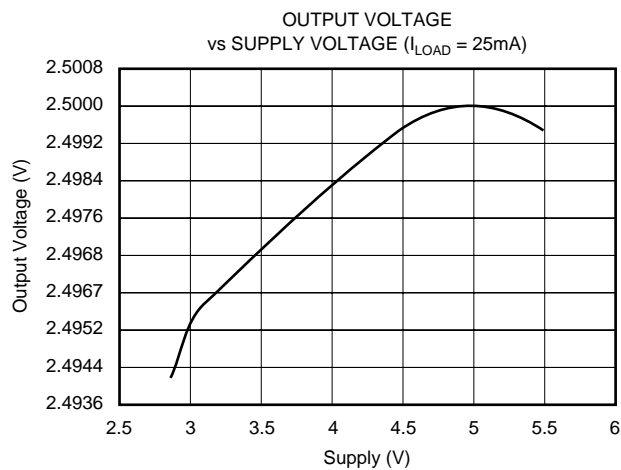
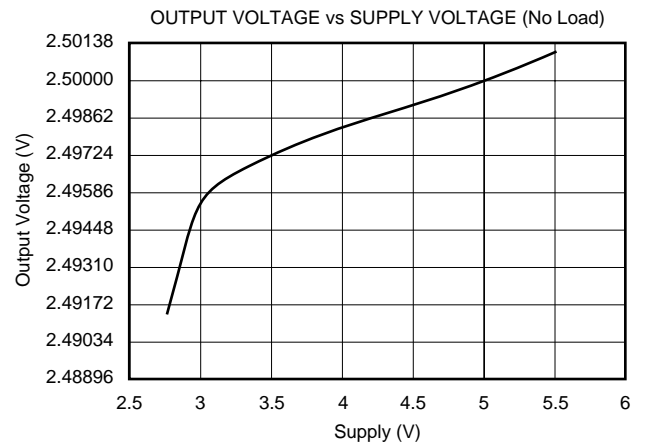
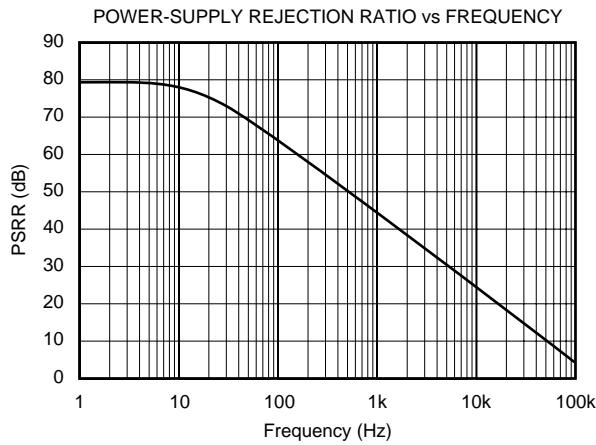
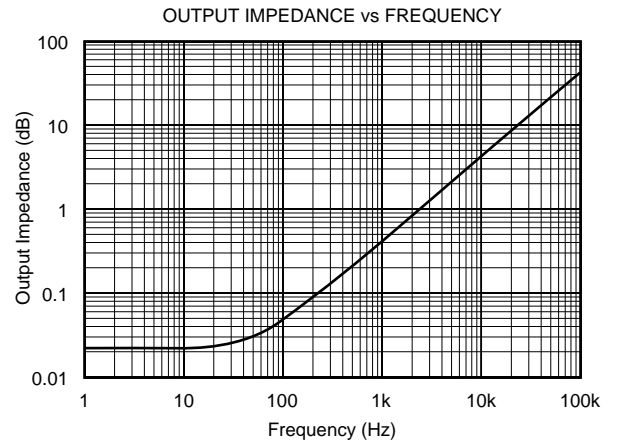
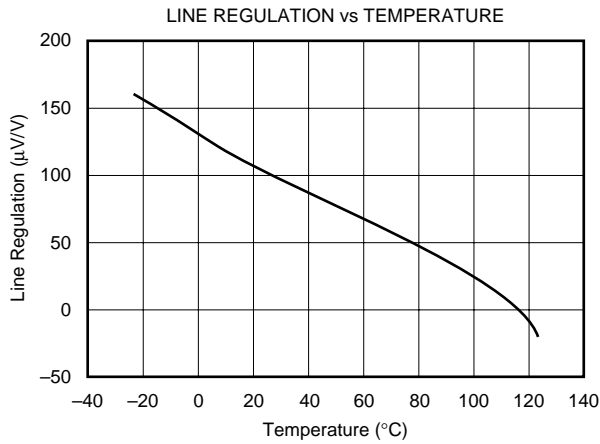
# TYPICAL CHARACTERISTICS

At  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = +5\text{V}$  power supply, REF2925 is used for typical characteristics, unless otherwise noted.



# TYPICAL CHARACTERISTICS (Cont.)

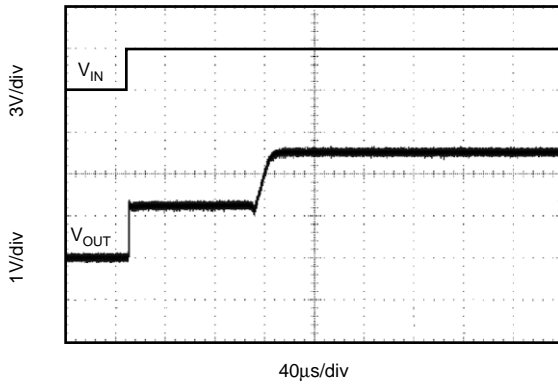
At  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = +5\text{V}$  power supply, REF2925 is used for typical characteristics, unless otherwise noted.



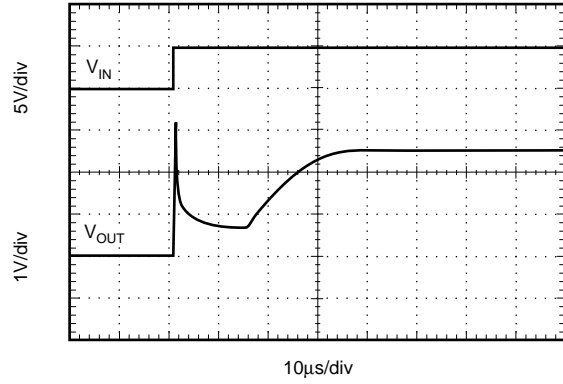
# TYPICAL CHARACTERISTICS (Cont.)

At  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = +5\text{V}$  power supply, REF2925 is used for typical characteristics, unless otherwise noted.

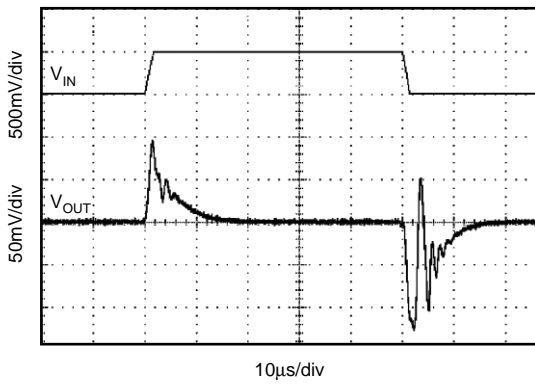
STEP RESPONSE,  $C_L = 0$ , 3V START-UP



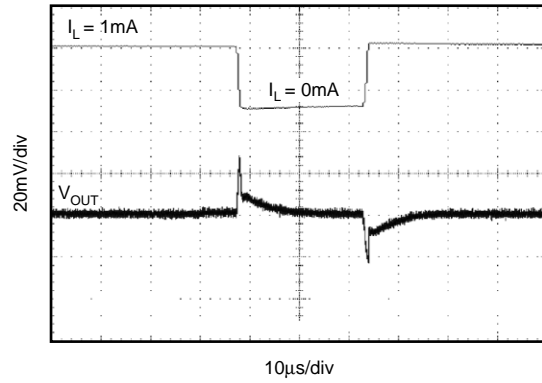
STEP RESPONSE,  $C_L = 0$ , 5V START-UP



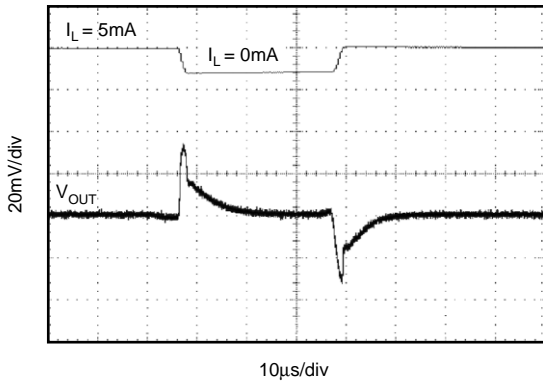
LINE TRANSIENT RESPONSE



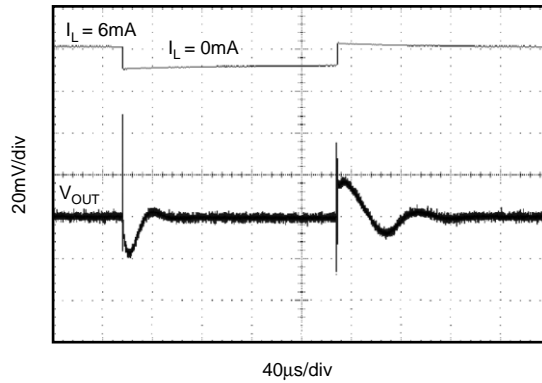
0-1mA LOAD TRANSIENT ( $C_L = 0$ )



0-5mA LOAD TRANSIENT ( $C_L = 0$ )

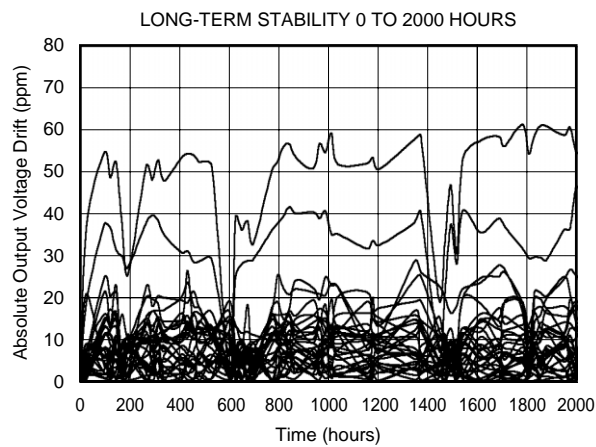
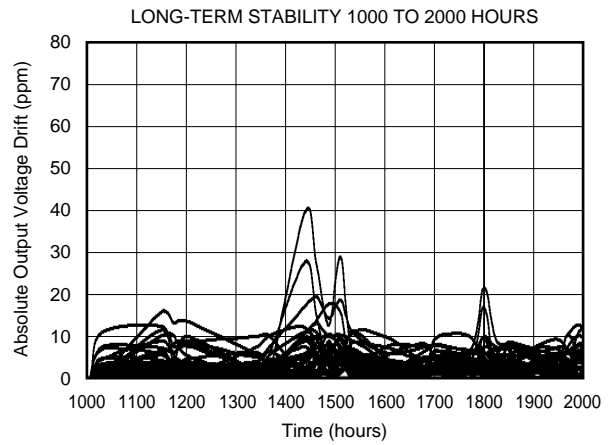
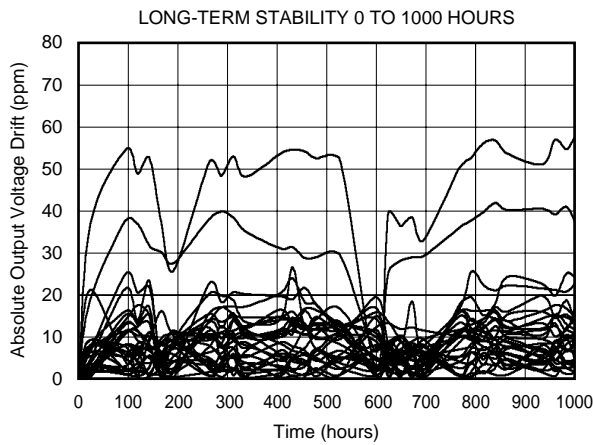
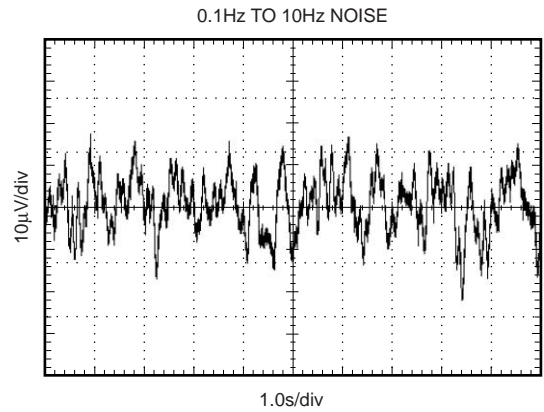
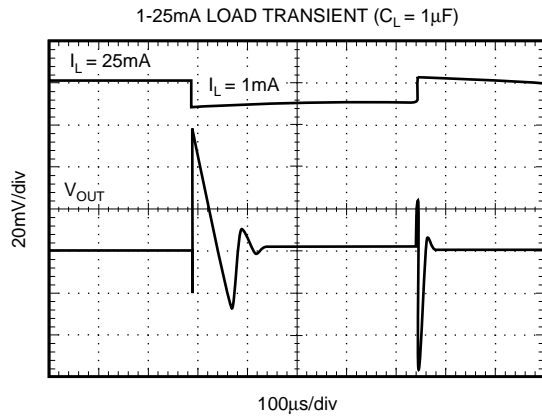


1-6mA LOAD TRANSIENT ( $C_L = 1\mu\text{F}$ )



# TYPICAL CHARACTERISTICS (Cont.)

At  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = +5\text{V}$  power supply, REF2925 is used for typical characteristics, unless otherwise noted.



# THEORY OF OPERATION

The REF29xx is a series, CMOS, precision bandgap voltage reference. Its basic topology is shown in Figure 1. The transistors  $Q_1$  and  $Q_2$  are biased such that the current density of  $Q_1$  is greater than that of  $Q_2$ . The difference of the two base-emitter voltages,  $V_{be1} - V_{be2}$ , has a positive temperature coefficient and is forced across resistor  $R_1$ . This voltage is gained up and added to the base-emitter voltage of  $Q_2$ , which has a negative coefficient. The resulting output voltage is virtually independent of temperature. The curvature of the bandgap voltage, as seen in the typical curve, *Output Voltage vs Temperature*, is due to the slightly nonlinear temperature coefficient of the base-emitter voltage of  $Q_2$ .

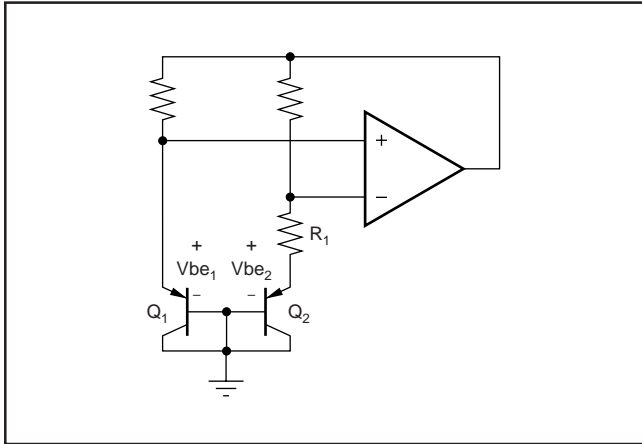


FIGURE 1. Simplified Schematic of Bandgap Reference.

## APPLICATION INFORMATION

The REF29xx does not require a load capacitor, and is stable with any capacitive load. Figure 2 shows typical connections required for operation of the REF29xx. A supply bypass capacitor of  $0.47\mu\text{F}$  is recommended.

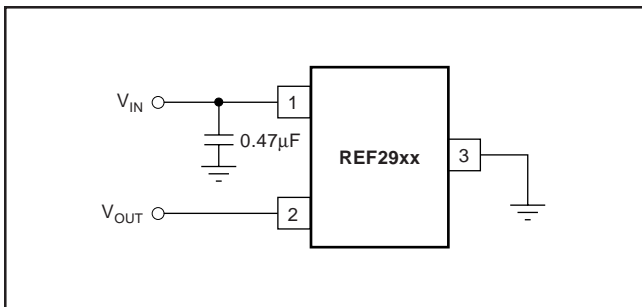


FIGURE 2. Typical Connections for Operating REF29xx.

### SUPPLY VOLTAGE

The REF29xx family of references features an extremely low dropout voltage. With the exception of the REF2912, which has a minimum supply requirement of 1.8V, the REF29xx can be operated with a supply of only 1mV above the output voltage in an unloaded condition. For loaded conditions, a typical dropout voltage versus load performance plot is shown on the cover page.

The REF29xx features a low quiescent current, which is extremely stable over changes in both temperature and supply. The typical room temperature quiescent current is  $42\mu\text{A}$ , and the maximum quiescent current over temperature is just  $59\mu\text{A}$ . Additionally, the quiescent current typically changes less than  $2.5\mu\text{A}$  over the entire supply range, as shown in Figure 3.

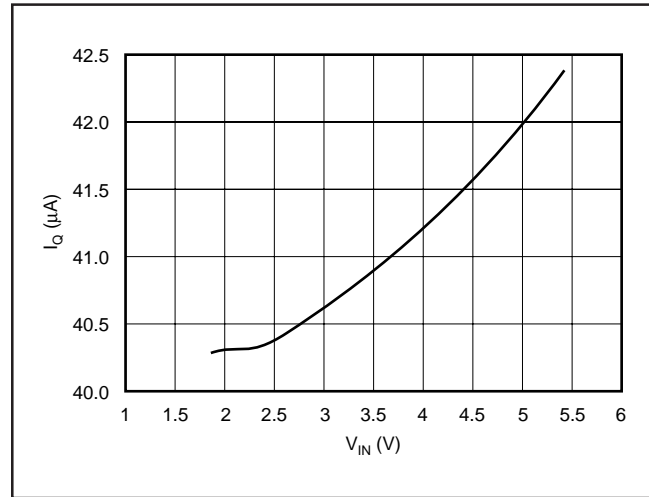


FIGURE 3. Supply Current vs Supply Voltage.

Supply voltages below the specified levels can cause the REF29xx to momentarily draw currents greater than the typical quiescent current. Using a power supply with a fast rising edge and low output impedance easily prevents this.

### THERMAL HYSTERESIS

Thermal hysteresis for the REF29xx is defined as the change in output voltage after operating the device at  $25^\circ\text{C}$ , cycling the device through the specified temperature range, and returning to  $25^\circ\text{C}$ , and can be expressed as:

$$V_{\text{HYST}} = \left( \frac{\text{abs}|V_{\text{PRE}} - V_{\text{POST}}|}{V_{\text{NOM}}} \right) \cdot 10^6 (\text{ppm})$$

Where:  $V_{\text{HYST}}$  = Calculated hysteresis

$V_{\text{PRE}}$  = Output voltage measured at  $25^\circ\text{C}$  pre-temperature cycling

$V_{\text{POST}}$  = Output voltage measured when device has been operated at  $25^\circ\text{C}$ , cycled through specified range  $-40^\circ\text{C}$  to  $+125^\circ\text{C}$  and returned to operation at  $25^\circ\text{C}$

### TEMPERATURE DRIFT

The REF29xx is designed to exhibit minimal drift error, defined as the change in output voltage over varying temperature. Using the *box* method of drift measurement, the REF29xx features a typical drift coefficient of 20ppm from  $0^\circ\text{C}$  to  $70^\circ\text{C}$ —the primary temperature range of use for many applications. For industrial temperature ranges of  $-40^\circ\text{C}$  to  $125^\circ\text{C}$ , the REF29xx family drift increases to a typical value of 50ppm.



## NOISE PERFORMANCE

The REF29xx generates noise less than  $50\mu\text{V}_{\text{PP}}$  between frequencies of 0.1Hz to 10Hz, and can be seen in the Typical Characteristic Curve, *0.1 to 10Hz Voltage Noise*. The noise voltage of the REF29xx increases with output voltage and operating temperature. Additional filtering may be used to improve output noise levels, although care should be taken to ensure the output impedance does not degrade ac performance.

## LONG TERM STABILITY

Long term stability refers to the change of the output voltage of a reference over a period of months or years. This effect lessens as time progresses as is apparent by the long term stability curves. The typical drift value for the REF29xx is 24ppm from 0-1000 hours, and 15ppm from 1000-2000 hours. This parameter is characterized by measuring 30 units at regular intervals for a period of 2000 hours.

## LOAD REGULATION

Load regulation is defined as the change in output voltage due to changes in load current. Load regulation for the REF29xx is measured using force and sense contacts as pictured in Figure 4. The force and sense lines tied to the

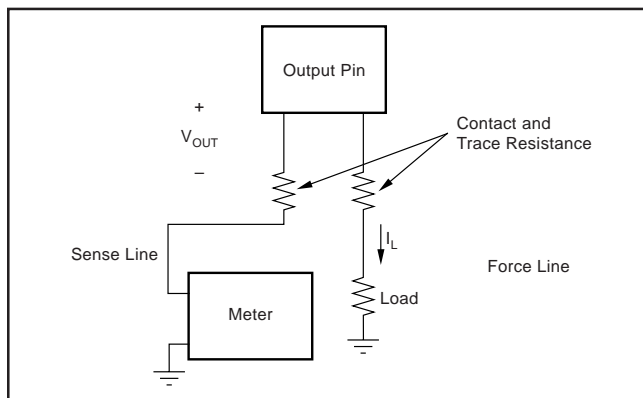


FIGURE 4. Accurate Load Regulation of REF29xx.

contact area of the output pin reduce the impact of contact and trace resistance, resulting in accurate measurement of the load regulation contributed solely by the REF29xx. For applications requiring improved load regulation, force and sense lines should be used.

## APPLICATION CIRCUITS

### Negative Reference Voltage

For applications requiring a negative and positive reference voltage, the OPA703 and REF29xx can be used to provide a dual supply reference from a  $\pm 5\text{V}$  supply. Figure 5 shows the REF2925 used to provide a  $\pm 2.5\text{V}$  supply reference voltage. The low offset voltage and low drift of the OPA703 complement the low drift performance of the REF29xx to provide an accurate solution for split-supply applications.

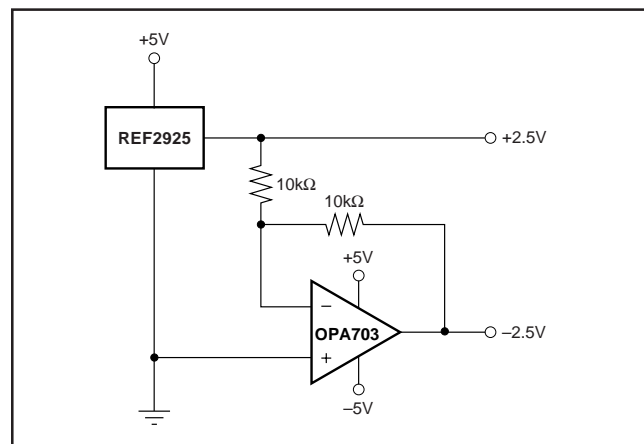


FIGURE 5. REF2925 Combined with OPA703 to Create Positive and Negative Reference Voltages.

## DATA ACQUISITION

Often data acquisition systems require stable voltage references to maintain necessary accuracy. The REF29xx family features stability and a wide range of voltages suitable for most micro-controllers and data converters. See Figure 6 for a basic data acquisition system.

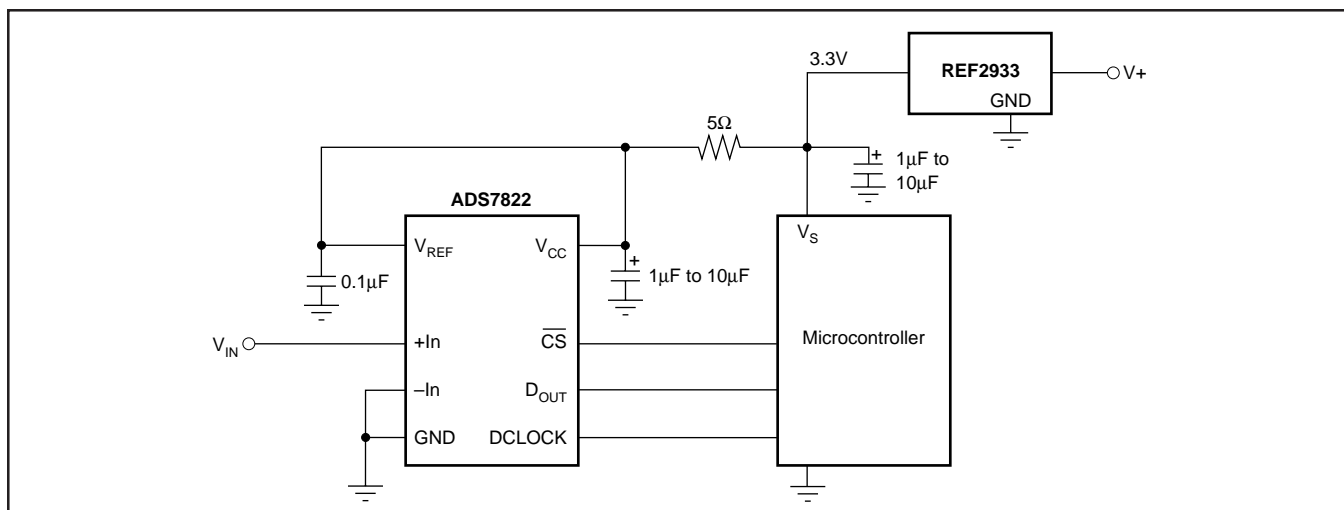


FIGURE 6. Basic Data Acquisition System 1.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
REF2912AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29A	<a href="#">Samples</a>
REF2912AIDBZRG4	ACTIVE	SOT-23	DBZ	3		TBD	Call TI	Call TI	-40 to 125		<a href="#">Samples</a>
REF2912AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29A	<a href="#">Samples</a>
REF2912AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29A	<a href="#">Samples</a>
REF2920AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29B	<a href="#">Samples</a>
REF2920AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29B	<a href="#">Samples</a>
REF2920AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29B	<a href="#">Samples</a>
REF2920AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29B	<a href="#">Samples</a>
REF2925AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29C	<a href="#">Samples</a>
REF2925AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29C	<a href="#">Samples</a>
REF2925AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29C	<a href="#">Samples</a>
REF2925AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29C	<a href="#">Samples</a>
REF2930AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29D	<a href="#">Samples</a>
REF2930AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29D	<a href="#">Samples</a>
REF2930AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29D	<a href="#">Samples</a>
REF2930AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29D	<a href="#">Samples</a>
REF2933AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29E	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
REF2933AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29E	<a href="#">Samples</a>
REF2933AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29E	<a href="#">Samples</a>
REF2933AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29E	<a href="#">Samples</a>
REF2940AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29F	<a href="#">Samples</a>
REF2940AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29F	<a href="#">Samples</a>
REF2940AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29F	<a href="#">Samples</a>
REF2940AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R29F	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

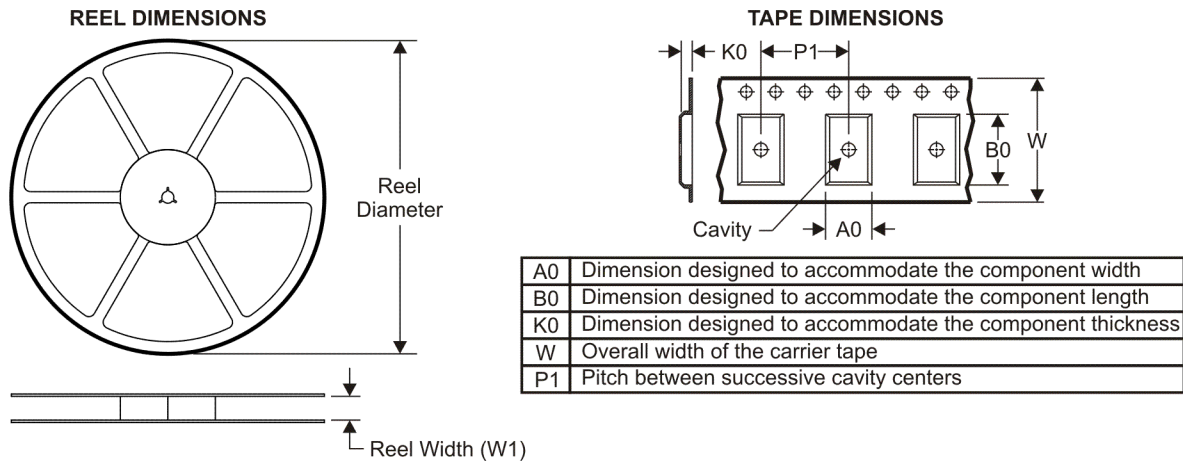
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

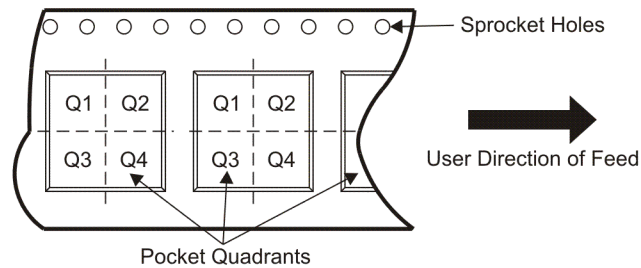
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
REF2912AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2912AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2920AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2920AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2925AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2925AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2930AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2930AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2933AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2933AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2940AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF2940AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3

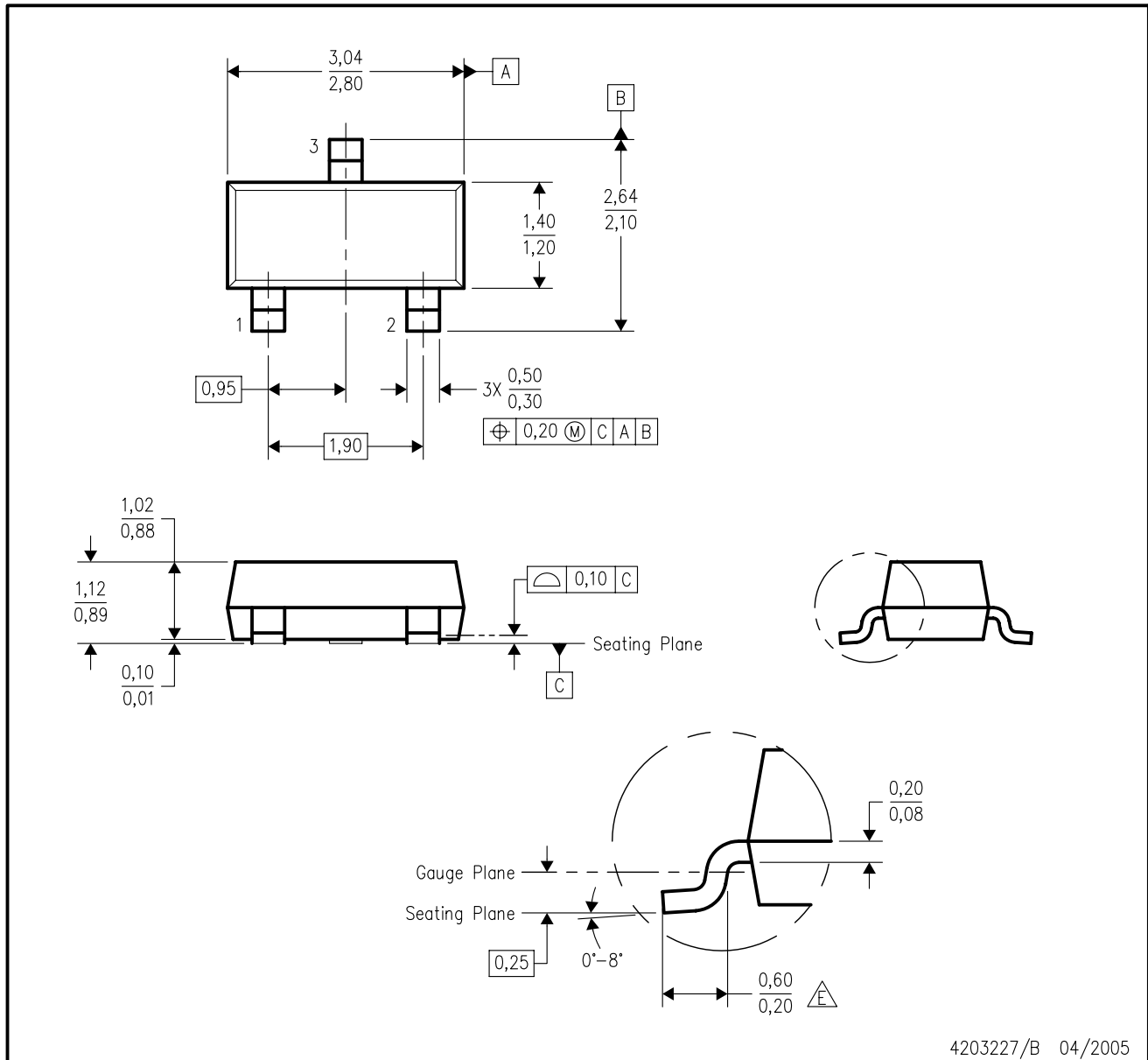
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
REF2912AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF2912AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF2920AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF2920AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF2925AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF2925AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF2930AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF2930AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF2933AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF2933AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF2940AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF2940AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE

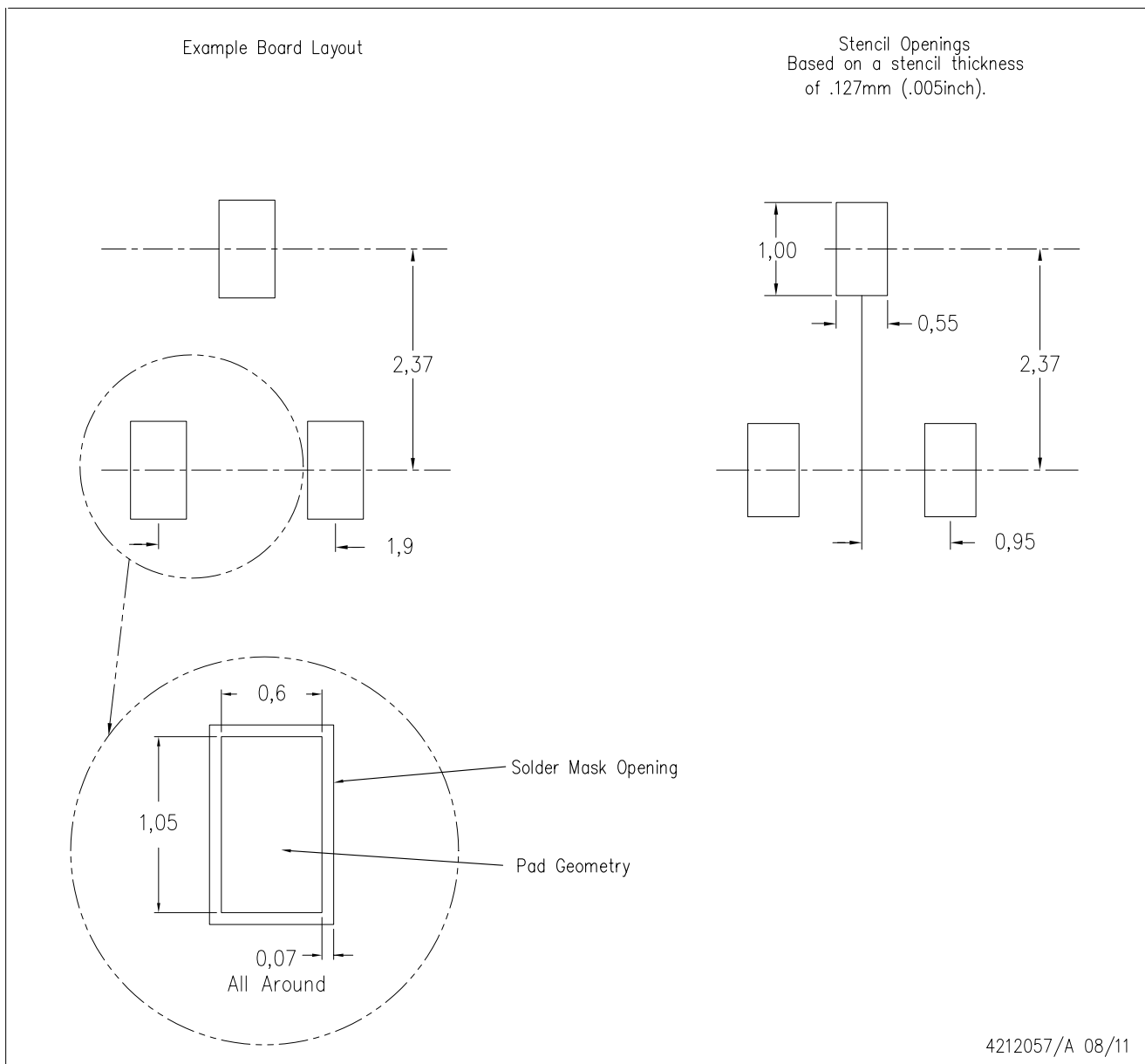


4203227/B 04/2005

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Lead dimensions are inclusive of plating.
  - D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
  - $\triangle E$  Falls within JEDEC TO-236 variation AB, except minimum foot length.

DBZ (R-PDSO-G3)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)